XPPC 24-200A

23.8" TFT FHD 16:9 Slim Bezel, Multi-touch screen Powered by 11th Generation Intel[®] Core[™] Processor





Main Features

- 23.8" TFT FHD 16:9 panel
- PCAP 10-point multi-touch with slim bezel design
- IP65-rated front panel
- Support: VESA/panel/open frame mount

- 11th Gen Intel[®] Core™ processor (Tiger Lake UP3)
- 1 x 260-pin DDR4 SO-DIMM up to 32G
- On-board M.2 2280 Key M PCIe x4 for storage module
- Support power input 12 VDC

Product Overview

The 23.8" fanless touchscreen computer XPPC 24-200A, powered by 11th Gen Intel® Core[™] i7/i5/i3 processors (Tiger Lake UP3), delivers exceptional graphics performance. With its integrated Intel® Iris Xe graphics, the XPPC 24-200A enables excellent AI inferencing performance. Compatibility with the Hailo-8 M.2 AI Acceleration Module makes it a suitable solution for AI-powered applications. Moreover, the XPPC 24-200A is equipped with a 10-point PCAP touchscreen, front IP65 protection, FHD wide viewing angle G series panel. Its slim profile and flexible mounting options make it well-suited for a variety of industrial applications, including Service Robots, Smart Warehouse, Smart City, and Smart Pharmacy.

Specifications

Panel

- LCD size: Innolux G-series 23.8", 16:9
- Resolution: Full HD 1920 x 1080
- Luminance
 - LCD panel: 350cd/m2
 - XPPC PCAP touch: 85% of panel's luminance after air bonding
- Contrast ratio: 1000:1
- LCD color: 16.7M
- Viewing angle: 89 (U), 89 (D), 89 (L), 89 (R)

Touch Screen

- 10-Point PCAP (Projected Capacitive Touch)
- Air bonding
- Glass surface treatment: AS + AG

System

- On-board 11th Generation Intel[®] Core[™] i3-1115G4E processor, Dual Core, 2.2 GHz base frequency, 6M Cache (formerly tiger lake-UP3)
 Intel[®] UHD graphics 630 on i3 processor
- On-board 11th Generation Intel[®] Core™ i5-1145G7E processor, Dual Core, 1.5 GHz base frequency, 8M cache
 - Intel[®] Iris[®] Xe graphics on i5 processor

Main Memory

 1 x 260-pin DDR4 SO-DIMM, supports non-ECC, un- buffered memory up to 32G

Storage Device

• 1 x M.2 2280 Key M SSD (support PCIe x4)

Expansion

• 1 x M.2 2230 Key E , support optional WiFi modules

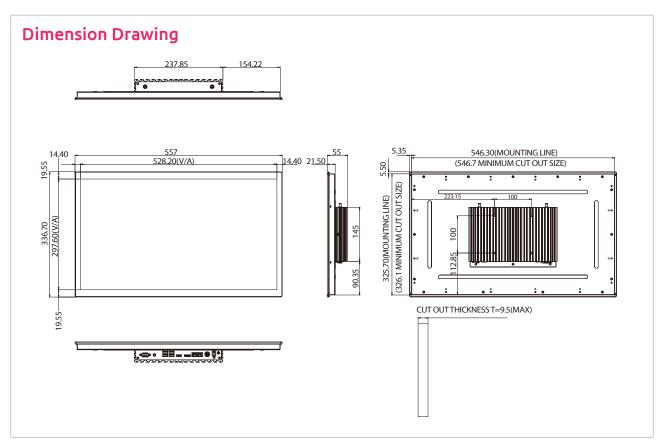
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- **Rear I/O** • 1 x 12V DC Jack
- 2 x RJ45 Intel[®] Gigabit LAN port
- 1 x DP++
- 1 x HDMI 2.0
- 4 x USB 3.0
- 1 x Line out
- 1 x RS232/422/485
- LED for Power on/off
- Power switch

Front I/O

• 2 x Antenna hole





Mechanical

- Color/materia: black metal sheet
- Support
 - VESA mount 100mm x 100mm
 - Panel mount
 - Open frame

Environment

- Vibration
 - IEC 68 2-64
 - 2G @ sine, 5~500Hz, 1hr/axis
- 2.2Grms @ random condition, 5~500Hz, 0.5hr/axis (non-operating)
- Shock
 - IEC 68 2-27
 - 20g peak acceleration (11 msec. duration)
- Temperature
 - Operating temperature: with 0.35 m/s air flow: 0°C~50°C
 - Storage temperature: -20°C~60°C
- Operating humidity: 10%~90% relative humidity, non-condensing limits to be at 90%

Dimensions

- System: 557mm x 336.7mm x 55mm
- System weight: 5.8 kg
- Package: 650mm x 480mm x 170mm
- Package weight: 7.85 kg

Power Supply

- 1 x 96W AC/DC lockable adapter included in accessory
- Input: 100VAC to 240VAC
- Output: DC+12VDC

Certifications

- CE (EN55035 + EN55032)
- FCC Class A (EMI part 15B)
- LVD (EN62368-1)

OS Support Lists

- Windows 10 64-bit
- Linux

Ordering Information

- XPPC24-200A-i3 (P/N:10W30XPPC37X0)
 23.8" FHD LED multi touchscreen computer, Intel[®] Core[™] i3-1115G4E
 Processor, w/air bonding
- XPPC24-200A-i5 (P/N: 10W30XPPC38X0) 23.8" FHD LED multi touchscreen computer, Intel® Core™ i5-1145G7E Processor, w/air bonding
- Panel mount kit (P/N: 88W30XPPC00X0)
- Open frame kit (P/N: 88W30XPPC01X0)

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